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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	FlexIO, I²C, IrDA, SPI, UART/USART
Peripherals	DMA, LCD, PWM, WDT
Number of I/O	54
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 20x16b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mkl33z32vlh4

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1.4 Voltage and current operating ratings

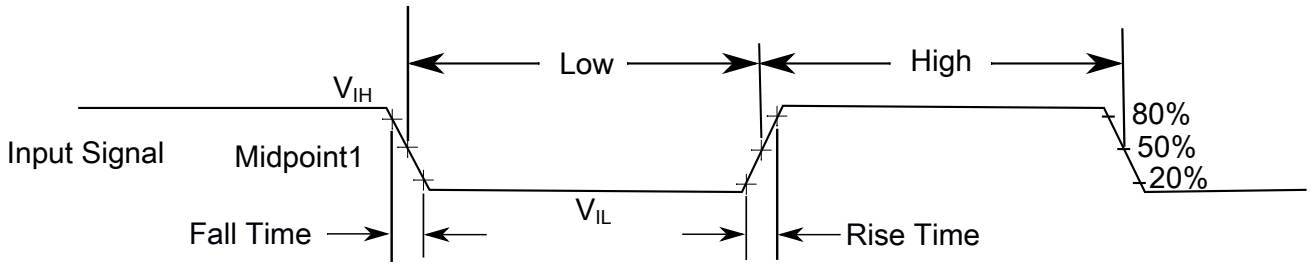
Table 4. Voltage and current operating ratings

Symbol	Description	Min.	Max.	Unit
V_{DD}	Digital supply voltage	–0.3	3.8	V
I_{DD}	Digital supply current	—	120	mA
V_{IO}	IO pin input voltage	–0.3	V_{DD} + 0.3	V
I_D	Instantaneous maximum current single pin limit (applies to all port pins)	–25	25	mA
V_{DDA}	Analog supply voltage	V_{DD} – 0.3	V_{DD} + 0.3	V

2 General

2.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.



The midpoint is V_{IL} + (V_{IH} - V_{IL}) / 2

Figure 1. Input signal measurement reference

All digital I/O switching characteristics, unless otherwise specified, assume that the output pins have the following characteristics.

- C_L=30 pF loads
- Slew rate disabled
- Normal drive strength

2.2 Nonswitching electrical specifications

Table 9. Power consumption operating behaviors (continued)

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
	clock disable, 2 MHz core / 0.5 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	119	178.5	µA	
I_{DD_VLPR}	Very-low-power run mode current— 2 MHz LIRC mode, While(1) loop in flash all peripheral clock disable, 125 kHz core / 31.25 kHz flash, V_{DD} = 3.0 V • at 25 °C	—	41	89.39	µA	
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in flash all peripheral clock disable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	277	360.1	µA	
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in flash all peripheral clock enable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	343	425.32	µA	
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in SRAM in all peripheral clock disable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	375	450	µA	
I_{DD_VLPR}	Very-low-power run mode current— 8 MHz LIRC mode, While(1) loop in SRAM all peripheral clock enable, 4 MHz core / 1 MHz flash, V_{DD} = 3.0 V • at 25 °C	—	441	529.2	µA	
I_{DD_VLPR}	Very-low-power run mode current—2 MHz LIRC mode, While(1) loop in SRAM all peripheral clock disable, 125 kHz core / 31.25 kHz flash, V_{DD} = 3.0 V • at 25 °C	—	45	103.5	µA	
I_{DD_WAIT}	Wait mode current—core disabled, 48 MHz system/24 MHz bus, flash disabled (flash doze enabled), all peripheral clocks disabled, MCG_Lite under HIRC mode, V_{DD} = 3.0 V • at 25 °C	—	2.14	2.50	mA	
I_{DD_WAIT}	Wait mode current—core disabled, 24 MHz system/12 MHz bus, flash disabled (flash doze enabled), all peripheral clocks disabled, MCG_Lite under HIRC mode, V_{DD} = 3.0 V • at 25 °C	—	1.41	1.62	mA	
I_{DD_VLPW}	Very-low-power wait mode current, core disabled, 4 MHz system/ 1 MHz bus and flash, all peripheral clocks disabled, V_{DD} = 3.0 V • at 25 °C	—	193	239.023	µA	

Table continues on the next page...

Table 10. Low power mode peripheral adders — typical value

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
$I_{IRC8MHz}$	8 MHz internal reference clock (IRC) adder. Measured by entering STOP or VLPS mode with 8 MHz IRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	85	87	88	88	89	90	µA
$I_{IRC2MHz}$	2 MHz internal reference clock (IRC) adder. Measured by entering STOP mode with the 2 MHz IRC enabled, MCG_SC[FCRDIV]=000b, MCG_MC[LIRC_DIV2]=000b.	28	28	28	28	28	28	µA
$I_{EREFSTEN4MHz}$	External 4 MHz crystal clock adder. Measured by entering STOP or VLPS mode with the crystal enabled.	206	224	230	238	245	253	µA
$I_{EREFSTEN32KHz}$	External 32 kHz crystal clock adder by means of setting the OSC0_CR[EREFSTEN and EREFSTEN] bits to 1 and SIM_SOPT1[OSC32KSEL] to 01. Measured by entering all modes with the crystal enabled. • VLLS1 • VLLS3 • LLS • VLPS • STOP	440 440 490 510 510	490 490 490 560 560	540 540 540 560 560	560 560 560 560 560	570 570 570 610 610	580 580 680 680 680	nA
I_{LPTMR}	LPTMR peripheral adder measured by placing the device in VLLS1 mode with LPTMR enabled using LPO.	30	30	30	85	100	200	nA
I_{CMP}	CMP peripheral adder measured by placing the device in VLLS1 mode with CMP enabled using the 6-bit DAC and a single external input for compare. Includes 6-bit DAC power consumption.	16	16	16	16	16	16	µA
I_{RTC}	RTC peripheral adder measured by placing the device in VLLS1 mode with external 32 kHz crystal enabled by means of the RTC_CR[OSCE] bit and the RTC ALARM set for 1 minute. Includes ERCLK32K (32 kHz external crystal) power consumption.	582	627	638	662	682	760	nA
I_{UART}	UART peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source waiting for RX data at 115200 baud rate.							

Table continues on the next page...

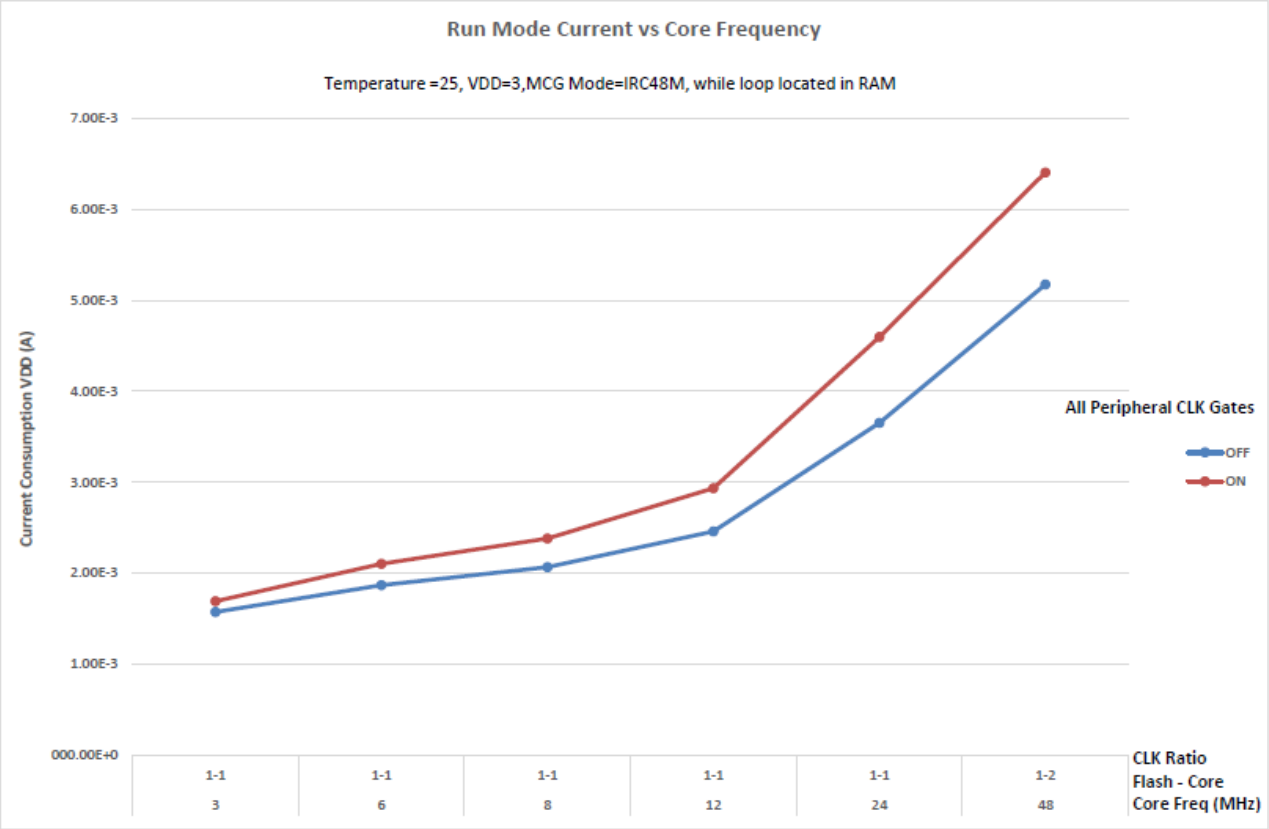
Table 10. Low power mode peripheral adders — typical value (continued)

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
	Includes selected clock source power consumption. • IRC8M (8 MHz internal reference clock) • IRC2M (2 MHz internal reference clock)	105 34	110 34	110 34	111 34	112 34	114 34	µA
I_{TPM}	TPM peripheral adder measured by placing the device in STOP or VLPS mode with selected clock source configured for output compare generating 100 Hz clock signal. No load is placed on the I/O generating the clock signal. Includes selected clock source and I/O switching currents. • IRC8M (8 MHz internal reference clock) • IRC2M (2 MHz internal reference clock)	130 40	130 40	130 40	130 40	130 40	130 40	µA
I_{BG}	Bandgap adder when BGEN bit is set and device is placed in VLPx or VLLSx mode.	45	45	45	45	45	45	µA
I_{ADC}	ADC peripheral adder combining the measured values at V_{DD} and V_{DDA} by placing the device in STOP or VLPS mode. ADC is configured for low power mode using the internal clock and continuous conversions.	320	320	320	320	320	320	µA
I_{LCD}	LCD peripheral adder measured by placing the device in VLLS1 mode with external 32 kHz crystal enabled by means of the OSC0_CR[EREFSTEN, EREFSTEN] bits. VIREG disabled, resistor bias network enabled, 1/8 duty cycle, 8 x 36 configuration for driving 288 Segments, 32 Hz frame rate, no LCD glass connected. Includes ERCLK32K (32 kHz external crystal) power consumption.	4.9	4.9	4.9	4.9	4.9	4.9	µA

2.2.5.1 Diagram: Typical IDD_RUN operating behavior

The following data was measured under these conditions:

- MCG-Lite in HIRC for run mode, and LIRC for VLPR mode
- No GPIOs toggled
- Code execution from flash
- For the ALLOFF curve, all peripheral clocks are disabled except FTFA


Run Mode Current vs Core Frequency
Temperature =25, VDD=3,MCG Mode=IRC48M, while loop located in RAM
Current Consumption VDD (A)
7.00E-3
6.00E-3
5.00E-3
4.00E-3
3.00E-3
2.00E-3
1.00E-3
000.00E+0
All Peripheral CLK Gates
OFF
ON
1-1 3
1-1 6
1-1 8
1-1 12
1-1 24
1-2 48
CLK Ratio
Flash - Core
Core Freq (MHz)

- AN1259: System Design and Layout Techniques for Noise Reduction in MCU-Based Systems
- KL-QRUG (Kinetis L-series Quick Reference).

2.2.7 Capacitance attributes

Table 11. Capacitance attributes

Symbol	Description	Min.	Max.	Unit
C_{IN}	Input capacitance	—	7	pF

2.3 Switching specifications

2.3.1 Device clock specifications

Table 12. Device clock specifications

Symbol	Description	Min.	Max.	Unit
Normal run mode				
f_{SYS}	System and core clock	—	48	MHz
f_{BUS}	Bus clock	—	24	MHz
f_{FLASH}	Flash clock	—	24	MHz
f_{LPTMR}	LPTMR clock	—	24	MHz
VLPR and VLPS modes[1]				
f_{SYS}	System and core clock	—	4	MHz
f_{BUS}	Bus clock	—	1	MHz
f_{FLASH}	Flash clock	—	1	MHz
f_{LPTMR}	LPTMR clock[2]	—	24	MHz
f_{LPTMR_ERCLK}	LPTMR external reference clock	—	16	MHz
$f_{osc\_hi\_2}$	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	—	16	MHz
f_{TPM}	TPM asynchronous clock	—	8	MHz
$f_{LPUART0/1}$	LPUART0/1 asynchronous clock	—	8	MHz

1. The frequency limitations in VLPR and VLPS modes here override any frequency specification listed in the timing specification for any other module. These same frequency limits apply to VLPS, whether VLPS was entered from RUN or from VLPR.
2. The LPTMR can be clocked at this speed in VLPR or VLPS only when the source is an external pin.

3.4 Memories and memory interfaces

3.4.1 Flash electrical specifications

This section describes the electrical characteristics of the flash memory module.

3.4.1.1 Flash timing specifications — program and erase

The following specifications represent the amount of time the internal charge pumps are active and do not include command overhead.

Table 21. NVM program/erase timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
t_{hvpgm4}	Longword Program high-voltage time	—	7.5	18	µs	—
$t_{hversscr}$	Sector Erase high-voltage time	—	13	113	ms	1
$t_{hversall}$	Erase All high-voltage time	—	52	452	ms	1

1. Maximum time based on expectations at cycling end-of-life.

3.4.1.2 Flash timing specifications — commands

Table 22. Flash command timing specifications

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$t_{rd1sec1k}$	Read 1s Section execution time (flash sector)	—	—	60	µs	1
t_{pgmchk}	Program Check execution time	—	—	45	µs	1
t_{rdrsrc}	Read Resource execution time	—	—	30	µs	1
t_{pgm4}	Program Longword execution time	—	65	145	µs	—
t_{ersscr}	Erase Flash Sector execution time	—	14	114	ms	2
t_{rd1all}	Read 1s All Blocks execution time	—	—	0.9	ms	1
t_{rdonce}	Read Once execution time	—	—	25	µs	1
$t_{pgmonce}$	Program Once execution time	—	65	—	µs	—
t_{ersall}	Erase All Blocks execution time	—	70	575	ms	2
t_{vfykey}	Verify Backdoor Access Key execution time	—	—	30	µs	1
$t_{ersallu}$	Erase All Blocks Unsecure execution time	—	70	575	ms	2

1. Assumes 25 MHz flash clock frequency.
2. Maximum times for erase parameters based on expectations at cycling end-of-life.

2. Typical values assume V_{DDA} = 3.0 V, Temp = 25 °C, f_{ADCK} = 2.0 MHz unless otherwise stated. Typical values are for reference only and are not tested in production.
3. The ADC supply current depends on the ADC conversion clock speed, conversion rate and ADC_CFG1[ADLPC] (low power). For lowest power operation, ADC_CFG1[ADLPC] must be set, the ADC_CFG2[ADHSC] bit must be clear with 1 MHz ADC conversion clock speed.
4. 1 LSB = $(V_{REFH} - V_{REFL})/2^N$
5. ADC conversion clock < 16 MHz, Max hardware averaging (AVGE = %1, AVGS = %11)
6. Input data is 100 Hz sine wave. ADC conversion clock < 12 MHz.
7. Input data is 1 kHz sine wave. ADC conversion clock < 12 MHz.
8. ADC conversion clock < 3 MHz

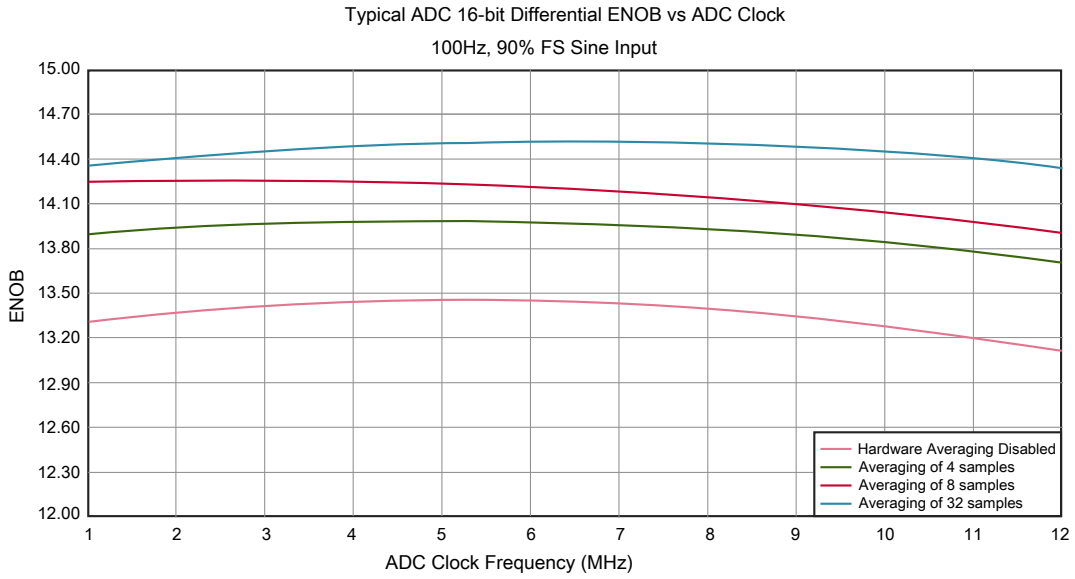


Figure 7. Typical ENOB vs. ADC_CLK for 16-bit differential mode

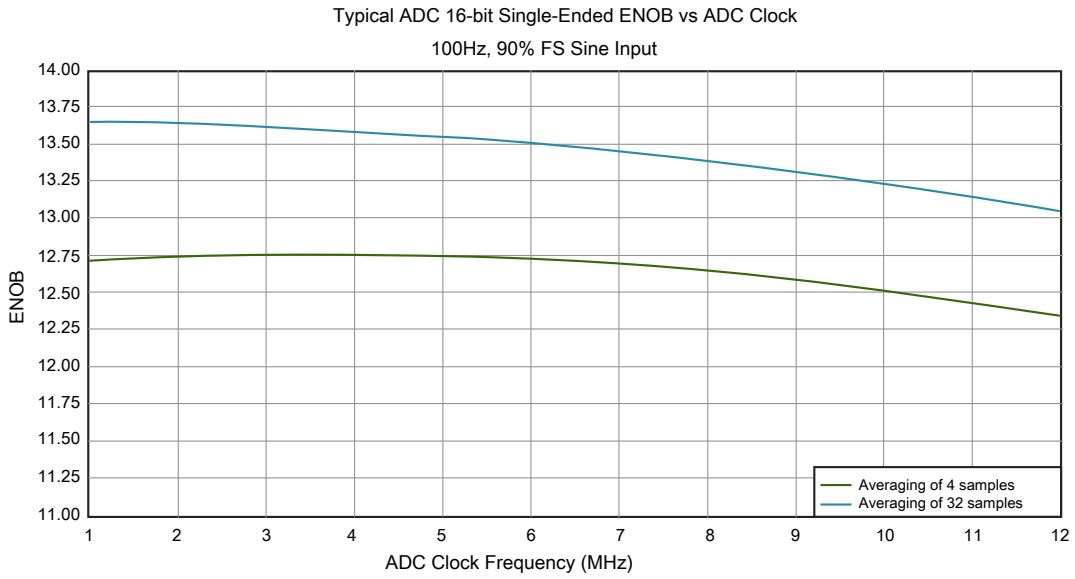


Figure 8. Typical ENOB vs. ADC_CLK for 16-bit single-ended mode

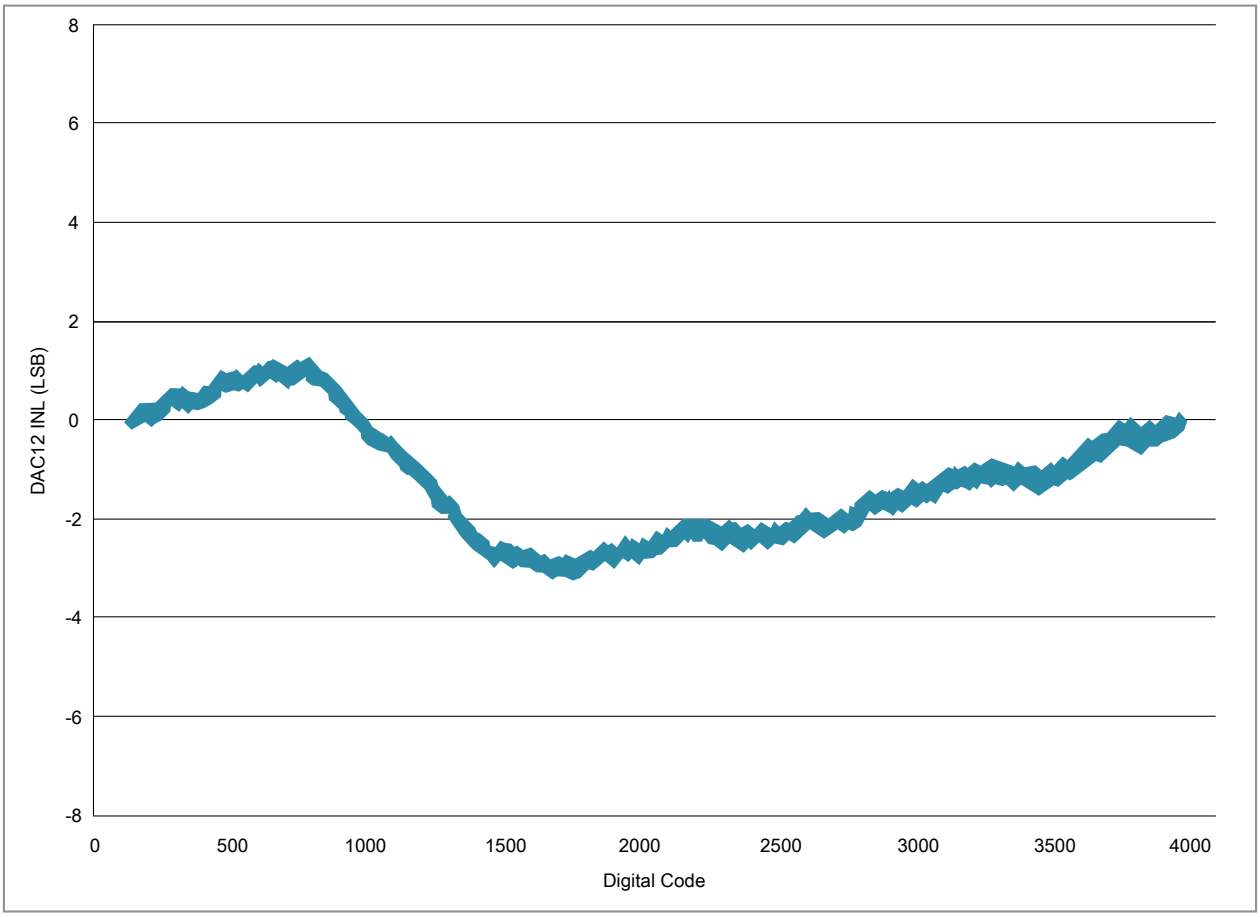
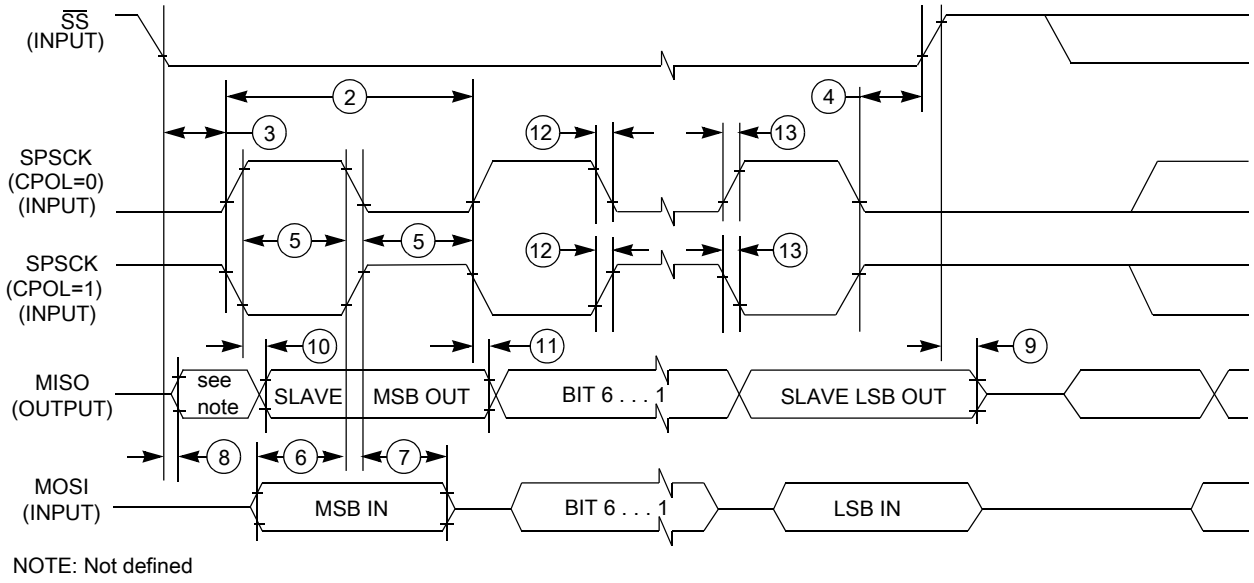


Figure 11. Typical INL error vs. digital code



NOTE: Not defined

Figure 16. SPI slave mode timing (CPHA = 1)

5.2 I²C

5.2.1 Inter-Integrated Circuit Interface (I2C) timing

Table 38. I2C timing

Characteristic	Symbol	Standard Mode		Fast Mode		Unit
		Minimum	Maximum	Minimum	Maximum	
SCL Clock Frequency	f_{SCL}	0	100	0	400[1]	kHz
Hold time (repeated) START condition. After this period, the first clock pulse is generated.	t_{HD}; STA	4	—	0.6	—	µs
LOW period of the SCL clock	t_{LOW}	4.7	—	1.25	—	µs
HIGH period of the SCL clock	t_{HIGH}	4	—	0.6	—	µs
Set-up time for a repeated START condition	t_{SU}; STA	4.7	—	0.6	—	µs
Data hold time for I²C bus devices	t_{HD}; DAT	0[2]	3.45[3]	0[4]	0.9[2]	µs
Data set-up time	t_{SU}; DAT	250[5]	—	100[3, 6]	—	ns
Rise time of SDA and SCL signals	t_r	—	1000	20 +0.1C_b[7]	300	ns
Fall time of SDA and SCL signals	t_f	—	300	20 +0.1C_b[6]	300	ns
Set-up time for STOP condition	t_{SU}; STO	4	—	0.6	—	µs
Bus free time between STOP and START condition	t_{BUF}	4.7	—	1.3	—	µs
Pulse width of spikes that must be suppressed by the input filter	t_{SP}	N/A	N/A	0	50	ns

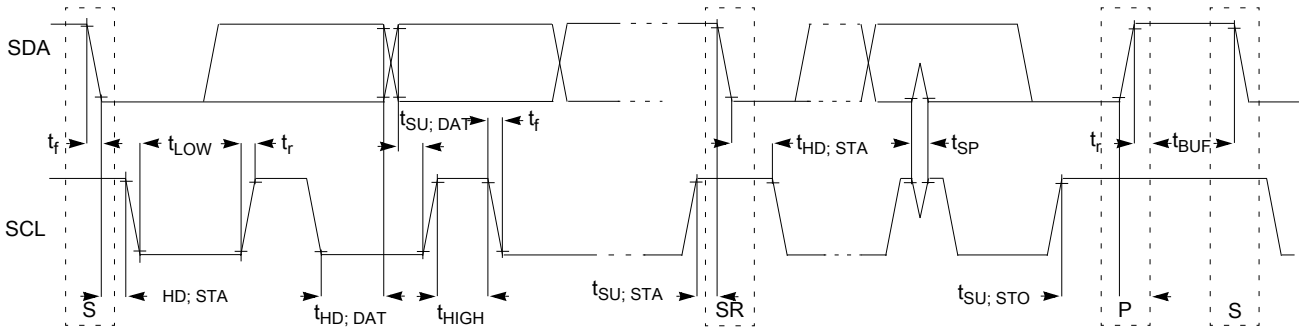


Figure 17. Timing definition for devices on the I²C bus

5.3 UART

See General switching specifications.

6 Design considerations

6.1 Hardware design considerations

This device contains protective circuitry to guard against damage due to high static voltage or electric fields. However, take normal precautions to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit.

6.1.1 Printed circuit board recommendations

- Place connectors or cables on one edge of the board and do not place digital circuits between connectors.
- Drivers and filters for I/O functions should be placed as close to the connectors as possible. Connect TVS devices at the connector to a good ground. Connect filter capacitors at the connector to a good ground.
- Physically isolate analog circuits from digital circuits if possible.
- Place input filter capacitors as close to the MCU as possible.
- For best EMC performance, route signals as transmission lines; use a ground plane directly under LQFP packages; and solder the exposed pad (EP) to ground directly under QFN packages.

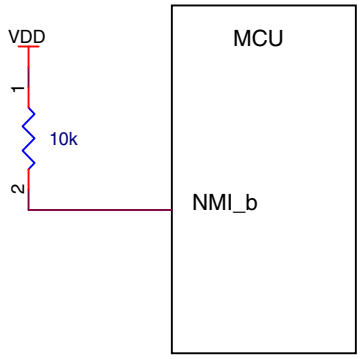


Figure 22. NMI pin biasing

- Debug interface

  This MCU uses the standard ARM SWD interface protocol as shown in the following figure. While pull-up or pull-down resistors are not required (SWD_DIO has an internal pull-up and SWD_CLK has an internal pull-down), external 10kΩ pull resistors are recommended for system robustness. Please note the RESET_b pin recommendations mentioned above.

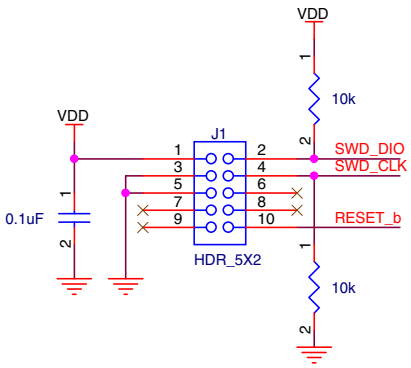


Figure 23. SWD debug interface

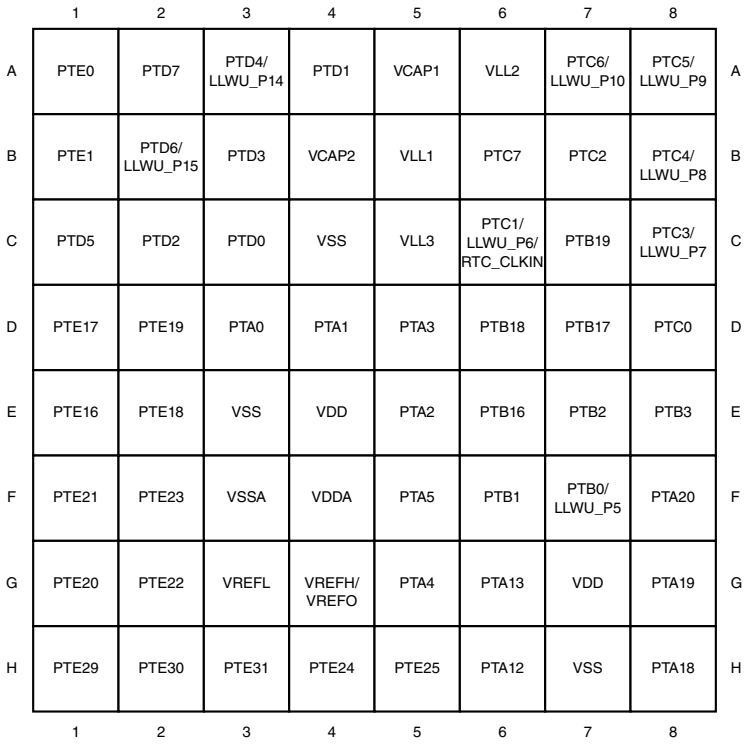
- Low leakage stop mode wakeup

  Select low leakage wakeup pins (LLWU_Px) to wake the MCU from one of the low leakage stop modes (LLS/VLLSx). Please refer to the signal multiplexing table for pin selection.

- Unused pin

  Unused GPIO pins should be left floating (no electrical connections) with the MUX field of the pin's PORTx_PCRn register equal to 0:0:0. This disables the digital input path to the MCU.

80 LQFP	64 LQFP	48 QFN	64 MAP BGA	Pin Name	Default	ALT0	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7
53	41	—	D6	PTB18	LCD_P14	LCD_P14	PTB18		TPM2_CH0				LCD_P14
54	42	—	C7	PTB19	LCD_P15	LCD_P15	PTB19		TPM2_CH1				LCD_P15
55	43	31	D8	PTC0	LCD_P20/ ADC0_SE14	LCD_P20/ ADC0_SE14	PTC0		EXTRG_IN		CMP0_OUT		LCD_P20
56	44	32	C6	PTC1/ LLWU_P6/ RTC_CLKIN	LCD_P21/ ADC0_SE15	LCD_P21/ ADC0_SE15	PTC1/ LLWU_P6/ RTC_CLKIN	I2C1_SCL		TPM0_CH0			LCD_P21
57	45	33	B7	PTC2	LCD_P22/ ADC0_SE11	LCD_P22/ ADC0_SE11	PTC2	I2C1_SDA		TPM0_CH1			LCD_P22
58	46	34	C8	PTC3/ LLWU_P7	LCD_P23	LCD_P23	PTC3/ LLWU_P7	SPI1_SCK	LPUART1_ RX	TPM0_CH2	CLKOUT		LCD_P23
59	47	35	E3	VSS	VSS	VSS							
60	48	36	C5	VLL3	VLL3	VLL3							
61	49	37	A6	VLL2	VLL2	VLL2/ LCD_P4	PTC20						LCD_P4
62	50	38	B5	VLL1	VLL1	VLL1/ LCD_P5	PTC21						LCD_P5
63	51	39	B4	VCAP2	VCAP2	VCAP2/ LCD_P6	PTC22						LCD_P6
64	52	40	A5	VCAP1	VCAP1	VCAP1/ LCD_P39	PTC23						LCD_P39
65	53	41	B8	PTC4/ LLWU_P8	LCD_P24	LCD_P24	PTC4/ LLWU_P8	SPI0_PCS0	LPUART1_ TX	TPM0_CH3	SPI1_PCS0		LCD_P24
66	54	42	A8	PTC5/ LLWU_P9	LCD_P25	LCD_P25	PTC5/ LLWU_P9	SPI0_SCK	LPTMR0_ ALT2			CMP0_OUT	LCD_P25
67	55	43	A7	PTC6/ LLWU_P10	LCD_P26/ CMP0_IN0	LCD_P26/ CMP0_IN0	PTC6/ LLWU_P10	SPI0_MOSI	EXTRG_IN		SPI0_MISO		LCD_P26
68	56	44	B6	PTC7	LCD_P27/ CMP0_IN1	LCD_P27/ CMP0_IN1	PTC7	SPI0_MISO			SPI0_MOSI		LCD_P27
69	—	—	—	PTC8	LCD_P28/ CMP0_IN2	LCD_P28/ CMP0_IN2	PTC8	I2C0_SCL	TPM0_CH4				LCD_P28
70	—	—	—	PTC9	LCD_P29/ CMP0_IN3	LCD_P29/ CMP0_IN3	PTC9	I2C0_SDA	TPM0_CH5				LCD_P29
71	—	—	—	PTC10	LCD_P30	LCD_P30	PTC10	I2C1_SCL					LCD_P30
72	—	—	—	PTC11	LCD_P31	LCD_P31	PTC11	I2C1_SDA					LCD_P31
73	57	—	C3	PTD0	LCD_P40	LCD_P40	PTD0	SPI0_PCS0		TPM0_CH0		FXIO0_D0	LCD_P40
74	58	—	A4	PTD1	LCD_P41/ ADC0_SE5b	LCD_P41/ ADC0_SE5b	PTD1	SPI0_SCK		TPM0_CH1		FXIO0_D1	LCD_P41
75	59	—	C2	PTD2	LCD_P42	LCD_P42	PTD2	SPI0_MOSI	UART2_RX	TPM0_CH2	SPI0_MISO	FXIO0_D2	LCD_P42
76	60	—	B3	PTD3	LCD_P43	LCD_P43	PTD3	SPI0_MISO	UART2_TX	TPM0_CH3	SPI0_MOSI	FXIO0_D3	LCD_P43
77	61	45	A3	PTD4/ LLWU_P14	LCD_P44	LCD_P44	PTD4/ LLWU_P14	SPI1_PCS0	UART2_RX	TPM0_CH4		FXIO0_D4	LCD_P44
78	62	46	C1	PTD5	LCD_P45/ ADC0_SE6b	LCD_P45/ ADC0_SE6b	PTD5	SPI1_SCK	UART2_TX	TPM0_CH5		FXIO0_D5	LCD_P45



	1	2	3	4	5	6	7	8	
A	PTE0	PTD7	PTD4/ LLWU_P14	PTD1	VCAP1	VLL2	PTC6/ LLWU_P10	PTC5/ LLWU_P9	A
B	PTE1	PTD6/ LLWU_P15	PTD3	VCAP2	VLL1	PTC7	PTC2	PTC4/ LLWU_P8	B
C	PTD5	PTD2	PTD0	VSS	VLL3	PTC1/ LLWU_P6/ RTC_CLKIN	PTB19	PTC3/ LLWU_P7	C
D	PTE17	PTE19	PTA0	PTA1	PTA3	PTB18	PTB17	PTC0	D
E	PTE16	PTE18	VSS	VDD	PTA2	PTB16	PTB2	PTB3	E
F	PTE21	PTE23	VSSA	VDDA	PTA5	PTB1	PTB0/ LLWU_P5	PTA20	F
G	PTE20	PTE22	VREFL	VREFH/ VREFO	PTA4	PTA13	VDD	PTA19	G
H	PTE29	PTE30	PTE31	PTE24	PTE25	PTA12	VSS	PTA18	H
	1	2	3	4	5	6	7	8	

Figure 30. 64 MAPBGA Pinout diagram

Figure below shows the 48 QFN pinouts:

11.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

11.2 Format

Part numbers for this device have the following format:

Q KL## A FFF R T PP CC N

11.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Table 42. Part number fields description

Field	Description	Values
Q	Qualification status	• M = Fully qualified, general market flow • P = Prequalification
KL##	Kinetis family	• KL33
A	Key attribute	• Z = Cortex-M0+
FFF	Program flash memory size	• 32 = 32 KB • 64 = 64 KB
R	Silicon revision	• (Blank) = Main • A = Revision after main
T	Temperature range (°C)	• V = –40 to 105
PP	Package identifier	• FT = 48 QFN (7 mm x 7 mm)[1] • LH = 64 LQFP (10 mm x 10 mm) • MP = 64 MAPBGA (5 mm x 5 mm)[1] • LK = 80 LQFP (12 mm x 12 mm)
CC	Maximum CPU frequency (MHz)	• 4 = 48 MHz
N	Packaging type	• R = Tape and reel

1. This package for this product is not yet available. However, it is included in Package Your Way program for Kinetis MCUs. Visit freescale.com/KPYW for more details.

11.4 Example

This is an example part number:

MKL33Z32VLH4

12 Terminology and guidelines

12.1 Definition: Operating requirement

An *operating requirement* is a specified value or range of values for a technical characteristic that you must guarantee during operation to avoid incorrect operation and possibly decreasing the useful life of the chip.

12.1.1 Example

This is an example of an operating requirement:

Symbol	Description	Min.	Max.	Unit
V_{DD}	1.0 V core supply voltage	0.9	1.1	V

12.2 Definition: Operating behavior

Unless otherwise specified, an *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

12.2.1 Example

This is an example of an operating behavior:

Symbol	Description	Min.	Max.	Unit
I_{WP}	Digital I/O weak pullup/ pulldown current	10	130	µA

12.8 Definition: Typical value

A *typical value* is a specified value for a technical characteristic that:

- Lies within the range of values specified by the operating behavior
- Given the typical manufacturing process, is representative of that characteristic during operation when you meet the typical-value conditions or other specified conditions

Typical values are provided as design guidelines and are neither tested nor guaranteed.

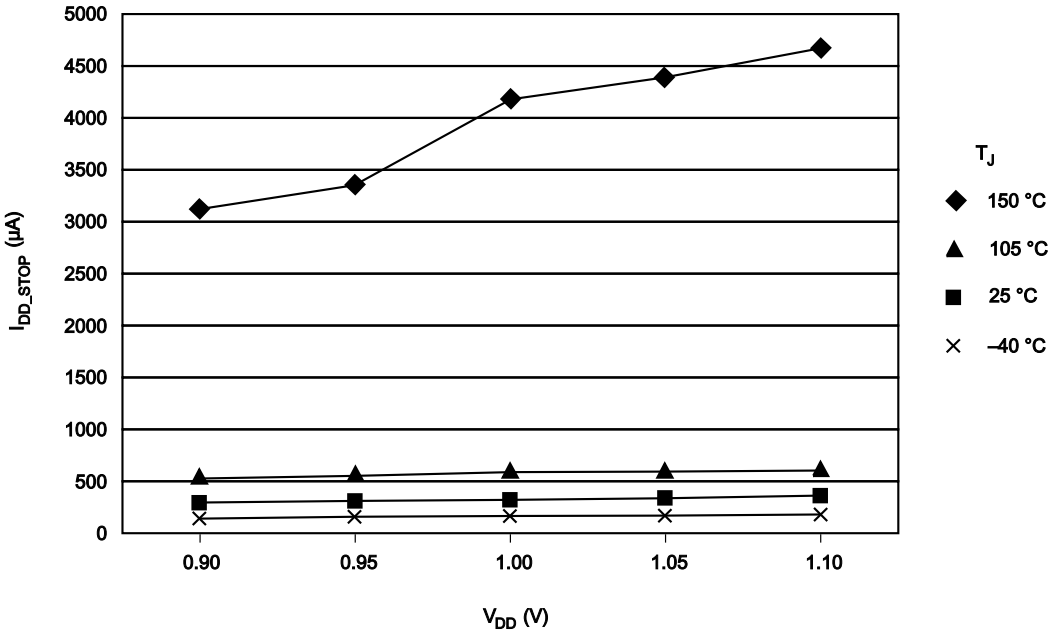
12.8.1 Example 1

This is an example of an operating behavior that includes a typical value:

Symbol	Description	Min.	Typ.	Max.	Unit
I_{WP}	Digital I/O weak pullup/pulldown current	10	70	130	µA

12.8.2 Example 2

This is an example of a chart that shows typical values for various voltage and temperature conditions:



12.9 Typical value conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Table 43. Typical value conditions

Symbol	Description	Value	Unit
T_A	Ambient temperature	25	°C
V_{DD}	3.3 V supply voltage	3.3	V

13 Revision History

The following table provides a revision history for this document.

Table 44. Revision History

Rev. No.	Date	Substantial Changes
1	01 February 2015	• Added new topic "Electrical Design Considerations" as Section 6. • Added a note in Table 14 - Thermal operating requirements. • Footnote 1 in Table 9 was moved in the beginning of the table as text.

Table continues on the next page...

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Document Number KL33P80M48SF3
Revision 2, 03/2015